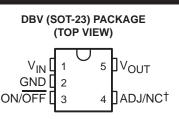
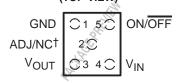
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- Available in the Texas Instruments NanoStar™ Chip Scale Package
- Fixed/ADJ Versions
- Output Tolerance of:
 0.75% (A Grade)
 1.25% (Standard Grade)
- Ultra-Low Dropout, Typically
 200 mV at Full Load of 100 mA
 7 mV at 1 mA
- Wide V_{IN} Range . . . 16 V Max
- Low I_Q . . . 600 μA Typ at Full Load of 100 mA
- Shutdown Current . . . 0.01 μA Typ
- Fast Transient Response to Line and Load
- Overcurrent and Thermal Protection
- High Peak Current Capability
- Portable Applications
 - Mobile Phones
 - Laptops
 - Personal Digital Assistants (PDAs)
 - Digital Cameras and Camcorders
 - CD and MP3 Players

description/ordering information



YEQ, YEU, YZQ, OR YZU (WCSP) PACKAGE (TOP VIEW)



[†] Must be left open in fixed-output versions

The LP2981 family of fixed-output, low-dropout regulators offers exceptional, cost-effective performance for both portable and nonportable applications. Available in adjustable version and in fixed voltages of 1.8 V, 2.5 V, 2.7 V, 2.8 V, 2.9 V, 3 V, 3.2 V, 3.3 V, 3.6 V, and 5 V, the family has an output tolerance of 0.75% for the A-grade devices (1.25% for the standard grade) and is capable of delivering 100-mA continuous load current. Standard regulator features, such as over-current and over-temperature protection, are included.

The LP2981 has features that make the regulator an ideal candidate for a variety of portable applications:

- Low dropout: A PNP pass element allows a typical dropout of 200 mV at 100-mA load current and 7 mV at 1-mA load.
- Low quiescent current: The use of a vertical PNP process allows for quiescent currents that are considerably lower than those associated with traditional lateral PNP regulators.
- Shutdown: A shutdown feature is available, allowing the regulator to consume only 0.01 μA when the ON/OFF pin is pulled low.
- Small packaging: For the most space-constraint needs, the regulator is available in SOT-23 package and NanoStar™ chip scale packaging. NanoStar package technology is a major breakthrough in IC packaging concepts, using the die as the package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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description/ordering information (continued)

Тј	PART GRADE	Vout (NOM)	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING [‡]
				Reel of 3000	LP2981DBVR	PREVIEW
		ADJ		Reel of 250	LP2981DBVT	
		4.05.1/		Reel of 3000	LP2981A-125DBVR	PREVIEW
		1.25 V		Reel of 250	LP2981A-125DBVT	PREVIEW
		1.8 V	Reel of 2 Reel of 3 Reel o	Reel of 3000	LP2981A-18DBVR	DDEVIEW
		1.8 V		Reel of 250	LP2981A-18DBVT	PREVIEW
		0.5.1/		Reel of 3000	LP2981A-25DBVR	PREVIEW
		2.5 V		Reel of 250	LP2981A-25DBVT	
	A grade: 0.75% tolerance	2.7 V		Reel of 3000	LP2981A-27DBVR	PREVIEW
				Reel of 250	LP2981A-27DBVT	
		2.8 V		Reel of 3000	LP2981A-28DBVR	LP6
4000 to 40500		2.0 V		Reel of 250	LP2981A-28DBVT	LP0_
-40°C to 125°C		2.0.1/		Reel of 3000	LP2981A-29DBVR	DDEVIEW
		2.9 V		Reel of 250	LP2981A-29DBVT	PREVIEW
		3 V		Reel of 3000	LP2981A-30DBVR	
		3 V		Reel of 250	LP2981A-30DBVT	LP8_
		3.2 V		Reel of 3000	LP2981A-32DBVR	PREVIEW
		3.2 V		Reel of 250	LP2981A-32DBVT	
		0.01/		Reel of 3000	LP2981A-33DBVR	1.00
		3.3 V		Reel of 250	LP2981A-33DBVT	LPC_
		2.0.1/		Reel of 3000	LP2981A-36DBVR	PREVIEW
		3.6 V		Reel of 250	LP2981A-36DBVT	
		F \/		Reel of 3000	LP2981A-50DBVR	PREVIEW
		5 V		Reel of 250	LP2981A-50DBVT	

ORDERING INFORMATION

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

[‡]DBV: The actual top-side marking has one additional character that designates the assembly/test site.



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ORDERING INFORMATION (continued)									
Тј	PART GRADE	V _{OUT} (NOM)	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING [‡]			
		ADJ			LP2981YEQR				
		1.25 V			LP2981A-125YEQR				
		1.8 V			LP2981A-18YEQR				
		2.5 V			LP2981A-25YEQR				
		2.7 V			LP2981A-27YEQR				
		2.8 V	NanoStar™ – WCSP 0.17-mm Bump (YEQ)	Reel of 3000	LP2981A-28YEQR				
	A grade:	2.9 V			LP2981A-29YEQR				
		3 V			LP2981A-30YEQR				
		3.2 V			LP2981A-32YEQR				
		3.3 V			LP2981A-33YEQR				
4000 to 40500		5 V			LP2981A-50YEQR				
-40°C to 125°C	0.75% tolerance	ADJ			LP2981YZQR				
		1.25 V			LP2981A-125YZQR				
		1.8 V			LP2981A-18YZQR				
		2.5 V			LP2981A-25YZQR				
		2.7 V	NanoFree™ – WCSP		LP2981A-27YZQR				
		2.8 V	0.17-mm Bump	Reel of 3000	LP2981A-28YZQR				
		2.9 V	(YZQ, Pb-free)		LP2981A-29YZQR				
		3 V			LP2981A-30YZQR				
		3.2 V			LP2981A-32YZQR				
		3.3 V			LP2981A-33YZQR				
		5 V			LP2981A-50YZQR				

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

[‡]YEQ/YZQ: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



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Тյ	PART GRADE	V _{OUT} (NOM)	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING [‡]
		ADJ			LP2981YEUR	
		1.25 V			LP2981A-125YEUR	
		1.8 V			LP2981A-18YEUR	
		2.5 V			LP2981A-25YEUR	
		2.7 V			LP2981A-27YEUR	
		2.8 V	NanoStar™ – WCSP 0.30-mm Bump (YEU)	Reel of 3000	LP2981A-28YEUR	
		2.9 V			LP2981A-29YEUR	
		3 V			LP2981A-30YEUR	
		3.2 V			LP2981A-32YEUR	
		3.3 V			LP2981A-33YEUR	-
4000 to 40500	A grade:	5 V			LP2981A-50YEUR	
-40°C to 125°C	0.75% tolerance	ADJ			LP2981YZUR	
		1.25 V			LP2981A-125YZUR	
		1.8 V			LP2981A-18YZUR	
		2.5 V			LP2981A-25YZUR	
		2.7 V	NanoFree™ – WCSP		LP2981A-27YZUR	
		2.8 V	0.30-mm Bump	Reel of 3000	LP2981A-28YZUR	
		2.9 V	(YZU, Pb-free)		LP2981A-29YZUR	
		3 V			LP2981A-30YZUR	
		3.2 V			LP2981A-32YZUR	
		3.3 V			LP2981A-33YZUR	
		5 V			LP2981A-50YZUR	

ORDERING INFORMATION (continued)

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

[‡]YEU/YZU: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



LP2981 **100-mA ULTRA-LOW DROPOUT REGULATOR** WITH SHUTDOWN SLVS521B – JULY 2004 – REVISED OCTOBER 2004

ORDERING INFORMATION (continued)								
Тј	PART GRADE	V _{OUT} (NOM)	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING [‡]		
				Reel of 3000	LP2981DBVR	DDEVIEW		
		ADJ		Reel of 250	LP2981DBVT	PREVIEW		
		4.05.1/		Reel of 3000	LP2981-125DBVR	DDEVIEW		
		1.25 V		Reel of 250	LP2981-125DBVT	PREVIEW		
		1.8 V		Reel of 3000	LP2981-18DBVR			
		1.8 V		Reel of 250	LP2981-18DBVT	PREVIEW		
				Reel of 3000	LP2981-25DBVR	PREVIEW		
	Standard grade: 1.25% tolerance	2.5 V		Reel of 250	LP2981-25DBVT			
		2.7 V		Reel of 3000	LP2981-27DBVR	PREVIEW		
		2.7 V		Reel of 250	LP2981-27DBVT			
			Reel of 250	Reel of 3000	LP2981-28DBVR	L D E		
–40°C to 125°C				Reel of 250	LP2981-28DBVT	LP5_		
-40°C 10 125°C		2.9 V	SOT-23 (DBV)	Reel of 3000	LP2981-29DBVR			
		2.9 V		Reel of 250	LP2981-29DBVT	PREVIEW		
		2.14		Reel of 3000	LP2981-30DBVR	1.07		
		3 V		Reel of 250	LP2981-30DBVT	LP7_		
		2.2.1/		Reel of 3000	LP2981-32DBVR	PREVIEW		
		3.2 V		Reel of 250	LP2981-32DBVT	FREVIEW		
		2.2.1/		Reel of 3000	LP2981-33DBVR			
		3.3 V		Reel of 250	LP2981-33DBVT	LPB_		
		2.0.1/		Reel of 3000	LP2981-36DBVR	PREVIEW		
		3.6 V		Reel of 250	LP2981-36DBVT			
		5 V		Reel of 3000	LP2981-50DBVR	PREVIEW		
		5 V		Reel of 250	LP2981-50DBVT			

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

[‡]DBV: The actual top-side marking has one additional character that designates the assembly/test site.



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TJ	PART GRADE	V _{OUT} (NOM)	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING [‡]
		ADJ			LP2981YEQR	
		1.25 V			LP2981-125YEQR	
		1.8 V			LP2981-18YEQR	
		2.5 V			LP2981-25YEQR	
		2.7 V			LP2981-27YEQR	
		2.8 V	NanoStar™ – WCSP 0.17-mm Bump (YEQ)	Reel of 3000	LP2981-28YEQR	
		2.8 V			LP2981-29YEQR	
		3 V	-		LP2981-30YEQR	
		3.2 V			LP2981-32YEQR	
		3.3 V			LP2981-33YEQR	7
4000 12 40500	Standard grade:	5 V			LP2981-50YEQR	
–40°C to 125°C	1.25% tolerance	ADJ			LP2981YZQR	
		1.25 V			LP2981-125YZQR	
		1.8 V			LP2981–18YZQR	
		2.5 V			LP2981-25YZQR	
		2.7 V	NanoFree™ – WCSP		LP2981-27YZQR	
		2.8 V	0.17-mm Bump	Reel of 3000	LP2981-28YZQR	
		2.8 V	(YZQ, Pb-free)		LP2981-29YZQR	
		3 V]		LP2981-30YZQR	
		3.2 V			LP2981-32YZQR	
		3.3 V			LP2981-33YZQR	
		5 V			LP2981-50YZQR	

ORDERING INFORMATION (continued)

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

[‡]YEQ/YZQ: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



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ORDERING INFORMATION (continued)									
Tj	PART GRADE	V _{OUT} (NOM)	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING [‡]			
		ADJ			LP2981YEUR				
		1.25 V	/		LP2981-125YEUR				
		1.8 V			LP2981-18YEUR				
		2.5 V			LP2981-25YEUR				
		2.7 V			LP2981-27YEUR				
		2.8 V	NanoStar™ – WCSP 0.30-mm Bump (YEU)	Reel of 3000	LP2981-28YEUR				
		2.8 V			LP2981-29YEUR				
		3 V			LP2981-30YEUR				
		3.2 V			LP2981-32YEUR				
	Standard grade: 1.25% tolerance	3.3 V			LP2981-33YEUR				
1000 / 10500		5 V			LP2981-50YEUR				
–40°C to 125°C		ADJ			LP2981YZUR				
		1.25 V			LP2981-125YZUR				
		1.8 V			LP2981-18YZUR				
		2.5 V			LP2981-25YZUR				
		2.7 V	NanoFree™ – WCSP		LP2981-27YZUR				
		2.8 V	0.30-mm Bump	Reel of 3000	LP2981-28YZUR				
		2.8 V	(YZU, Pb-free)		LP2981-29YZUR				
		3 V			LP2981-30YZUR				
		3.2 V			LP2981-32YZUR				
		3.3 V	1		LP2981-33YZUR				
		5 V			LP2981-50YZUR				

ODDEDING INFORMATION (<u>,</u> --n

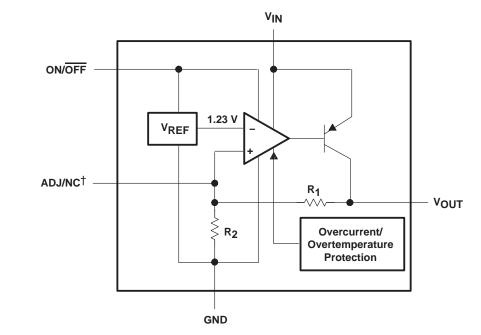
[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

[‡]YEU/YZU: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



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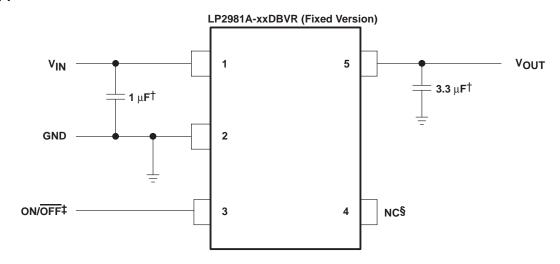
functional block diagram



[†] Fixed versions: Must be left open ADJ versions: $R_1 = \infty$, $R_2 = \infty$



basic application circuit

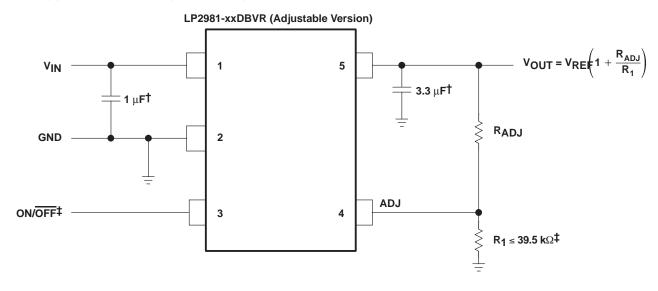


[†] Minimum C_{out} value for stability (can be increased without limit for improved stability and transient response) [‡] ON/OFF must be actively terminated. Connect to V_{IN} if shutdown feature is not used. § Must be left open

Figure 2







[†] Minimum C_{out} value for stability (can be increased without limit for improved stability and transient response) [‡] See Application Information

[‡]See Application Information

Figure 3

absolute maximum ratings over the virtual junction temperature range (unless otherwise noted)[†]

Continuous input voltage range, V _{IN}
Output voltage range (see Note 1) -0.3 V to 9 V
Input/output voltage differential range, VIN-VOUT (see Note 2)
Output current, I _{OUT} (see Note 3) Internally limited (short-circuit protected)
Package thermal impedance, θ_{JA} (see Notes 3 and 4): DBV package 206°C/W
YEQ/YZQ package TBD°C/W
YEU/YZU package TBD°C/W
Operating virtual junction temperature, T _J 150°C
Storage temperature range, T _{stg} –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. If load is returned to a negative power supply, the output must be diode clamped to GND.

 The PNP pass transistor has a parasitic diode connected between the input and output. This diode normally is reverse biased (V_{IN} > V_{OUT}), but will be forward biased if the output voltage exceeds the input voltage by a diode drop (see Application Information for more details).

3. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

4. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions

		MIN	MAX	UNIT
VIN	Supply input voltage	2.2†	16	V
VON/OFF	ON/OFF input voltage	0	V_{IN}	V
VIN-VOUT	Input-output differential	0.7	11	V
ΙΟυτ	Output current		100	mA
Тј	Virtual junction temperature	-40	125	°C

[†] Minimum V_{IN} of 2.2 V is needed for proper biasing of LDO control circuitry.

elect<u>rical</u> characteristics at specified free-air temperature range, $V_{IN} = V_{OUT(NOM)} + 1 V$, $V_{ON/OFF} = 2 V$, $C_{IN} = 1 \mu$ F, IL = 1 mA, $C_{OUT} = 4.7 \mu$ F, ADJ version: ADJ connected to V_{OUT} (unless otherwise noted)

			_	LP	2981A->	(X	L	P2981-X	Х		
PARA	METER	TEST CONDITIONS	TA	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
	Output voltage	IL = 1 mA	25°C	-0.75		0.75	-1.25		1.25		
∆Vout	tolerance		25°C	-1		1	-2		2	%VNOM	
(see Note 5)	$I_L = 1 \text{ mA to } 100 \text{ mA}$	–40°C to 125°C	-2.5		2.5	-3.5		3.5	-		
	Output voltage	VIN =	25°C		0.007	0.014		0.007	0.014		
$\Delta V_{OUT} / \Delta V_{IN}$	line regulation	[VOUT(NOM) + 1 V] to 16 V	-40°C to 125°C			0.032			0.032	%/V	
			25°C		1	3		1	3		
		I _L = 0	-40°C to 125°C			5			5		
			25°C		7	10		7	10		
., .,	Dropout	I _L = 1 mA	–40°C to 125°C			15			15		
VIN-VOUT	voltage (see Note 6)	L 05 A	25°C		70	100		70	100	mV	
	(00011010-0)	I _L = 25 mA	–40°C to 125°C			150			150		
		400 4	25°C		200	250		200	250		
		I _L = 100 mA	–40°C to 125°C			375			375		
			25°C		65	95		65	95		
		$I_{L} = 0$	–40°C to 125°C			125			125		
			25°C		80	110		80	110		
		I _L = 1 mA	–40°C to 125°C			170			170		
		L 05 A	25°C		200	300		200	300		
IGND	Ground pin current	I _L = 25 mA	–40°C to 125°C			550			550	μA	
	current		25°C		600	800		600	800		
		I _L = 100 mA	-40°C to 125°C			1500			1500		
		V _{ON/OFF} < 0.3 V (OFF)	25°C		0.01	0.8		0.01	0.8		
			–40°C to 105°C		0.05	2		0.05	2		
		V _{ON/OFF} < 0.15 V (OFF)	-40°C to 125°C			5			5		
			25°C		1.4			1.4			
—	ON/OFF input	High = O/P ON	–40°C to 125°C	1.6			1.6			v	
VON/OFF	voltage (see Note 7)		25°C		0.5			0.5			
	(000 11010 7)	Low = O/P OFF	-40°C to 125°C			0.15			0.15		

NOTES: 5. $V_{OUT} = V_{REF}$ for ADJ version

 Dropout voltage is defined as the input-to-output differential at which the output voltage drops 100 mV below the value measured with a 1-V differential. This dropout specification does not apply to the 1.8-V option, as the minimum V_{IN} = 2.2 V must be observed for proper biasing of LDO control circuitry.

7. The ON/OFF input must be actively terminated. Connect to VIN if this function is not used (see Application Information).



elect<u>rical</u> characteristics at specified free-air temperature range, $V_{IN} = V_{OUT(NOM)} + 1 V$, $V_{ON/OFF} = 2 V$, $C_{IN} = 1 \mu$ F, IL = 1 mA, $C_{OUT} = 4.7 \mu$ F, ADJ version: ADJ connected to V_{OUT} (unless otherwise noted) (continued)

			-	LP2981A-XX			LP2981-XX			
PARAI	METER	TEST CONDITIONS T _A		MIN	TYP	MAX	MIN	TYP	MAX	UNIT
			25°C		0.01			0.01		
1	ON/OFF input	$V_{ON/OFF} = 0$	$-40^{\circ}C$ to $125^{\circ}C$			-1			-1	
ION/OFF	current		25°C		5			5		μA
		$V_{ON/OFF} = 5 V$	$-40^{\circ}C$ to $125^{\circ}C$			15			15	
IOUT(PK)	Peak output current	Vout≥Vout(NOM)-5%	25°C	150	400		150	400		mA
Vn	Output noise voltage (RMS)	BW = 300 Hz to 50 kHz, C_{OUT} = 10 μ F	25°C		160			160		μV
$\Delta V_{OUT} / \Delta V_{IN}$	Ripple rejection	f = 1kHz, C _{OUT} = 10 μF	25°C		63			63		dB
IOUT(MAX)	Short-circuit current	R _L = 0 (steady state)	25°C		150			150		mA



APPLICATION INFORMATION

capacitors

input capacitor (Cin)

A minimum value of 1 μ F (over the entire operating temperature range) is required at the input of the LP2981. In addition, this input capacitor should be located within 1 cm of the input pin and connected to a clean analog ground. There is no Equivalent Series Resistance (ESR) requirement for this capacitor, and the capacitance can be increased without limit. A good quality ceramic or tantalum capacitor can be used.

output capacitor (Cout)

As a PNP regulator, the LP2981 requires the output capacitor to meet both a minimum capacitance and ESR value. Required ESR values as a function of load current are provided for various output voltages, load currents, and capacitances (see Figures 1–4).

Minimum Cout: 3.3 µF (can be increased without limit to improve transient response stability margin)

ESR range: see Figures 1-4

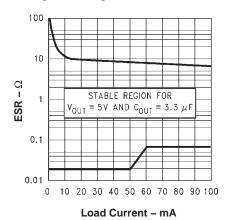


Figure 4. 5-V/3.3-µF ESR Curves

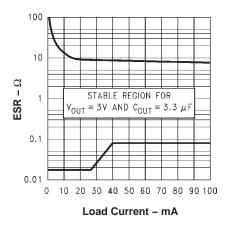


Figure 6. 3-V/3.3- μ F ESR Curves

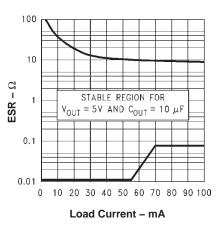


Figure 5. 5-V/10- μ F ESR Curves

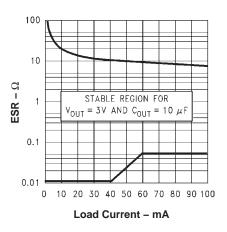


Figure 7. 3-V/10-µF ESR Curves



APPLICATION INFORMATION

output capacitor (Cout) (continued)

It is critical that both the minimum capacitance and ESR requirement be met over the entire operating temperature range. Depending on the type of capacitor used, both of these parameters can vary significantly with temperature (see capacitor characteristics section).

capacitor characteristics

ceramics

Due to their very low ESR values, ceramic capacitors are not suitable for use as the output capacitor. For instance, a typical 2.2- μ F ceramic capacitor has an ESR in the range of 10 m Ω to 20 m Ω and, thus, easily can fall out of minimum ESR requirements under certain operating conditions.

If a ceramic capacitor is used at the output, a $1-\Omega$ resistor should be placed in series with the capacitor to raise the ESR seen by the regulator.

tantalum

Solid tantalum capacitors are optimal choices for the LP2981, but they still must meet the minimum ESR requirement. Note that the ESR of a tantalum capacitor increases as temperature drops, as much as double from 25° C to -40° C. Thus, ESR margins must be maintained over the temperature range to prevent regulator instability. For operation at very low temperatures, paralleling a tantalum capacitor with a ceramic one keeps the combined ESR from increasing near the upper limit of the ESR curve.

aluminum

Aluminum capacitors can be used, but use with the LP2981 is impractical due to their large physical dimensions. They also must meet the ESR requirements over the full temperature range. In this regard, aluminium capacitors are at a big disadvantage due to their sharp ESR increase as temperature drops. For example, over a temperature drop from 20° C to -40° C, the ESR of an aluminum electrolytic capacitor can increase by a factor of 50. In addition, some of the electrolytes used in these capacitors can freeze at -25° C, making the capacitor nonoperational.

ON/OFF operation

The LP2981 allows for a shutdown mode via the ON/OFF pin. If the shutdown feature is not used, ON/OFF should be connected to the input to ensure that the regulator is on at all times. To drive ON/OFF:

- A LOW (≤0.3 V) turns the regulator OFF; a HIGH (≥1.6 V) turns it ON.
- Use either a totem-pole output or an open-collector output with a pullup resistor tied to V_{IN} (or another logic supply). The HIGH signal can exceed V_{IN}, but must not exceed the absolute maximum ratings of 20 V for the ON/OFF pin.
- Apply a signal with a slew rate of ≥40 mV/µs. A slow slew rate can cause the shutdown function to operate incorrectly.

ADJ version

From Figure 3, V_{OUT} is set according to the following equation:

$$V_{OUT} = V_{REF} \left(1 + \frac{R_{ADJ}}{R_1} \right)$$

where $V_{REF} = 1.23$ V (nominal). Under no-load conditions, a minimum "bias" current is required through the R_{ADJ} and R_1 divider to maintain regulator stability. Therefore, the maximum value for R_1 should be ~ 39.5 k Ω .

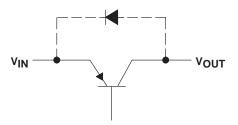


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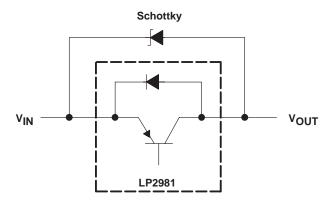
APPLICATION INFORMATION

reverse input-output voltage

An inherent diode is present across the PNP pass element of the LP2981.



With the anode connected to the output, this diode is reverse biased during normal operation, since the input voltage is higher than the output. However, if the output is pulled one VBE higher than the input, or if the input is abruptly stepped below the output, this diode is forward biased and can cause a parasitic silicon-controlled rectifier (SCR) to latch, resulting in current flowing from the output to the input (values in excess of 100 mA can cause damage). Thus, to prevent possible damage to the regulator in any application where the output may be pulled above the input, an external Schottky diode must be connected between the output and input. With the anode on output, this Schottky limits the reverse voltage across the output and input pins to ~ 0.3 V, preventing the regulator's internal diode from forward biasing.



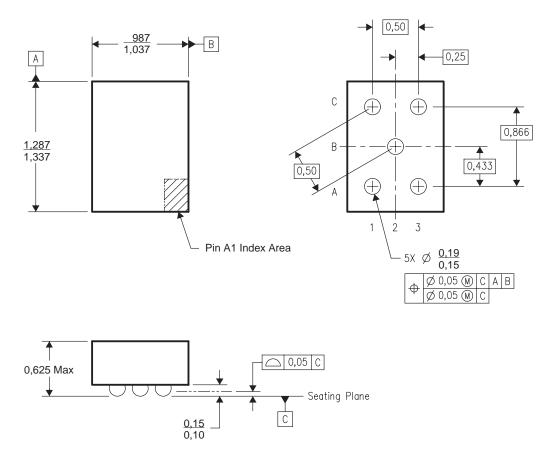
pin 4: NC

Pin 4 must be left OPEN. Do not connect anything to this pin, as it is used for post package trim.



WAFER CHIP SCALE INFORMATION

LP2981x-xxYEQ NanoStar (0.17-mm Bump) LP2981x-xxYZQ NanoFree (0.17-mm Pb-Free Bump)



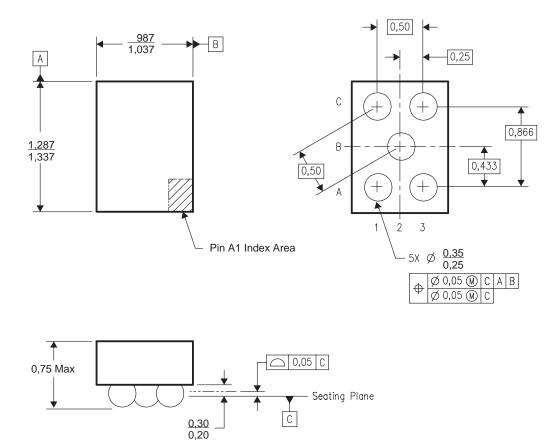
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. NanoStar package configuration.
- D. This package is tin-lead (SnPb); consult the factory for availability of lead-free material.



WAFER CHIP SCALE INFORMATION

LP2981x-xxYEU NanoStar (0.30-mm Bump) LP2981x-xxYZU NanoFree (0.30-mm Pb-Free Bump)



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. NanoStar package configuration.
- D. This package is tin-lead (SnPb); consult the factory for availability of lead-free material.



24-Jun-2005

PACKAGING INFORMATION

TEXAS INSTRUMENTS www.ti.com

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
LP2981-28DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981-28DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981-28DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981-28DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981-30DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981-30DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981-30DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981-30DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981-33DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981-33DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981-33DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981-33DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981A-28DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981A-28DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981A-28DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981A-28DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981A-30DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981A-30DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981A-30DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981A-30DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981A-33DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981A-33DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981A-33DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
LP2981A-33DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

 $^{(1)}$ The marketing status values are defined as follows:



ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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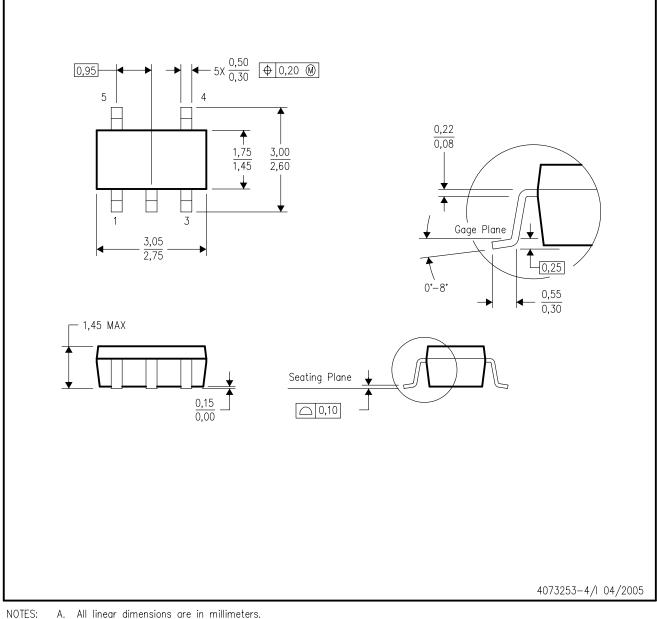
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



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